

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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RGB LED LIGHT ENGINE

Light Emitting Diodes (LEDs) offer many advantages over traditional incandescent lamps. Lamina's innovative LED arrays provide a revolutionary improvement in the LED market by creating the highest density packaging of discrete LED die. Developed using Lamina's multilayer Low Temperature Co-Fired Ceramic on Metal (LTCC-M) technology, Lamina LED array packages feature:

- SUPERIOR THERMAL PERFORMANCE
- SMALL SIZE
- INDEPENDANT COLOR CONTROLS
- HIGH FLUX DENSITY

Thermal performance is the key to achieving high luminous densities, high reliability and long life. Lamina's LTCC-M packaging allows LED devices (die) to be mounted directly to an engineered metal core without submounts. This creates the optimum thermal path to conduct heat away from the LED device. The result is that multiple devices can be located in close proximity while maintaining target LED junction temperatures.

Standard arrays are available in several different colors and light intensity outputs. These arrays can be mounted together to create strips of light or larger arrays. Terminals are supplied with a solderable surface finish to enable users to connect arrays to driver circuitry or other arrays in a series or parallel circuit.



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Typical Applications

SIGNAGE & CHANNEL LETTERS

- VIDEO DISPLAY BOARDS
- LED BILLBOARDS
- JUMBOTRON SIGNS

ARCHITECTURAL LIGHTING

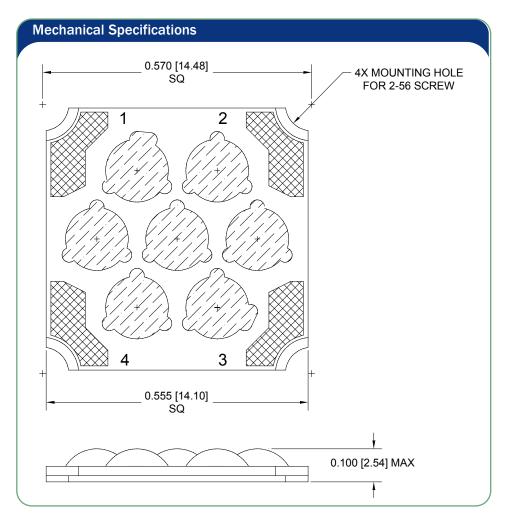
- DECORATIVE AND MINI-ACCENT
- COVE AND UNDER-SHELF
- GARDEN AND PATHWAY
- STEP LIGHTS

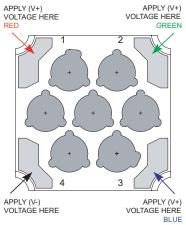
LCD BACKLIGHT

- COMPUTER DISPLAYS
- HEADS UP DISPLAYS



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Notes

OPTICAL RECOMMENDATIONS

Lamina's BL Series Light
Engines project a Lambertain
radiation pattern, with
projection angles built into
the package cavity at
approximately 150°. It will be
necessary for users to create
an optical reflector and lens
structure that meet their light
dispersion requirements.
Please contact Lamina
Application Engineering for
support with your optical
needs.

HEAT SINK RECOMMENDATIONS

Lamina's BL Series Light Engines are created with a heat spreader fabricated into the ceramic package. This heat spreader provides the most efficient thermal path from the die junction to the heat sink. The operational die junction temperature must not be allowed to exceed 125°C and should ideally be maintained as close to 25°C as possible. With increasing power levels, die junction temperature will rise and light output efficiency will drop. These variables must be taken into consideration when selecting a light engine for your application. Please contact **Lamina Application Engineering for support with** your thermal management needs.



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Technical Data					
Part # BL-22F0-0132	Symbol	Min	Typical	Max	Unit
Wavelength	\mathbf{R} λ	624	-	635	nm
	Gλ	520	-	540	nm
	Β λ	465	-	475	nm
Voltage*	RV_F	-	3	-	V
	GV_F	-	4	-	V
	B V _F	-	4	-	V
Drive Current	R I _F	-	0.63	-	Α
	GI_F	-	0.63	-	Α
	B I _F	-	0.21	-	Α
Power*	R P	-	1.89	-	W
	G P	-	2.52	-	W
	ВР	-	0.84	-	W
Luminous Flux*	R Φ_{V}	29	59	-	lm
	G Φ_{V}	1 5	31	-	lm
	B Φ_{V}	2.1	4.2	-	lm
Thermal Resistance	T_{R}	-	2.25	3	°C/W

*Note 1. Optical and Electrical specifications are given for the specified drive current at a 25°C junction temperature.

Typical Beam Pattern L I G H T I N T E N S I T Y -90 -60 -30 0 30 60 90



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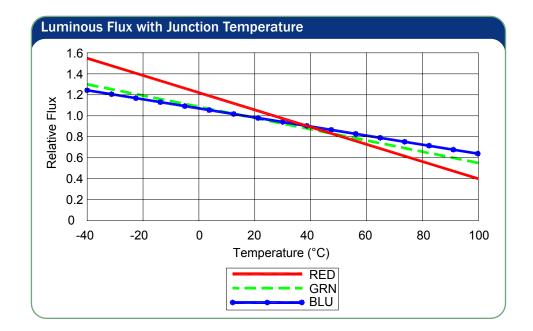
Notes

ATTACHMENT RECOMMENDATIONS

Lamina's BL Series Light
Engines are configured with
solder pads compatible with
Sn63 or Sn62 solder. As with
many electrical devices, nonacid RMA type solder flux
should be used to prepare the
solder pads before
application of solder. If
attachment is performed with
a soldering iron, care must be
taken to minimize heat
transfer to the die and
minimize leaching of the
solderable pads.



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Notes

ASSEMBLY RECOMMENDATIONS

Lamina's BL Series Light
Engines, are designed for
attachment to heatsinks with
conductive epoxy or screw
down for flange mount
devices with thermal grease
in the joint. In limited cases,
thermal transfer tape can be
used, but will generally result
in higher than desired
thermal resistance creating
excessive heat and reducing
light output and die life.



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Specifications subject to change without notice.